

## General Description

The WSF3015 is the highest performance trench N-ch and P-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSF3015 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

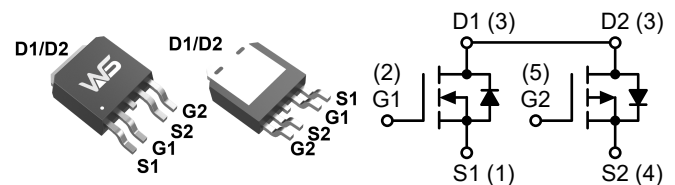
## Product Summary

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
30V	15mΩ	22A
-30V	25mΩ	-19A

## Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- CCFL Back-light Inverter

## TO-252-4L Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V <sub>DS</sub>	Drain-Source Voltage	30	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	±20	V
I <sub>D</sub>	Continuous Drain Current, V <sub>GS(NP)</sub> =10V, T <sub>c</sub> =25 °C	22	-19	A
	Continuous Drain Current, V <sub>GS(NP)</sub> =10V, T <sub>c</sub> =100 °C	10	-8	A
I <sub>DP</sub> <sup>a</sup>	Pulse Drain Current Tested, V <sub>GS(NP)</sub> =10V	52	-45	A
E <sub>AS</sub> <sup>c</sup>	Avalanche Energy, Single pulse, L=0.5mH	22	45	mJ
I <sub>AS</sub> <sup>c</sup>	Avalanche Current, Single pulse, L=0.5mH	21	-30	A
P <sub>D</sub>	Total Power Dissipation, T <sub>c</sub> =25 °C	18	18	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	150	150	°C
R <sub>θJA</sub> <sup>b</sup>	Thermal Resistance-Junction to Ambient, Steady State	62	62	°C/W
R <sub>θJC</sub>	Thermal Resistance-Junction to Case, Steady State	5.0	5.0	°C/W

Note \* : Max. current is limited by bonding wire.

Note a : Pulse width limited by max. junction temperature.

Note b : R<sub>θJA</sub> steady state t=999s. R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup>, FR-4 board with 2oz. Copper.

Note c : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T<sub>j</sub>=25°C).

**N-Channel Electrical Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$R_{DS(ON)}^d$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=10A$	---	15	22	m $\Omega$
		$V_{GS}=4.5V, I_D=5A$	---	20	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.6	2.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=20V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	uA
		$V_{DS}=20V, V_{GS}=0V, T_J=85^\circ C$	---	---	30	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	2.5	5.0	$\Omega$
$Q_g^e$	Total Gate Charge	$V_{DS}=20V, V_{GS}=4.5V, I_{DS}=10A$	---	7.2	---	nC
$Q_{gs}^e$	Gate-Source Charge		---	1.4	---	
$Q_{gd}^e$	Gate-Drain Charge		---	2.2	---	
$T_{d(on)}^e$	Turn-On Delay Time	$V_{DD}=15V, I_{DS}=5A, V_{GS}=10V, R_G=3.3R.$	---	4.1	---	ns
$T_r^e$	Rise Time		---	9.8	---	
$T_{d(off)}^e$	Turn-Off Delay Time		---	15.5	---	
$T_f^e$	Fall Time		---	6.0	---	
$C_{iss}^e$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	572	---	pF
$C_{oss}^e$	Output Capacitance		---	81	---	
$C_{rss}^e$	Reverse Transfer Capacitance		---	65	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V, \text{Force Current}$	---	---	10	A
$V_{SD}^d$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1.2	V

Note d : Pulse test ; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

Note e : Guaranteed by design, not subject to production testing.

**P-Channel Electrical Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	---	---	V
$R_{DS(ON)}^d$	Static Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-7A$	---	25	33	m $\Omega$
		$V_{GS}=-4.5V, I_D=-5A$	---	37	54	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.0	---	-2.8	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ C$	---	---	-1	uA
		$V_{DS}=-20V, V_{GS}=0V, T_J=85^\circ C$	---	---	-30	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$Q_g^e$	Total Gate Charge	$V_{DS}=-15V, V_{GS}=-4.5V, I_D=-12A$	---	9.8	---	nC
$Q_{gs}^e$	Gate-Source Charge		---	2.2	---	
$Q_{gd}^e$	Gate-Drain Charge		---	3.4	---	
$T_{d(on)}^e$	Turn-On Delay Time	$V_{DD}=-15V, V_{GS}=-10V, R_G=6\Omega, I_D=-1A, R_L=15\Omega,$	---	16.4	---	ns
$T_r^e$	Rise Time		---	20.2	---	
$T_{d(off)}^e$	Turn-Off Delay Time		---	55	---	
$T_f^e$	Fall Time		---	10	---	
$C_{iss}^e$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$	---	930	---	pF
$C_{oss}^e$	Output Capacitance		---	148	---	
$C_{rss}^e$	Reverse Transfer Capacitance		---	115	---	

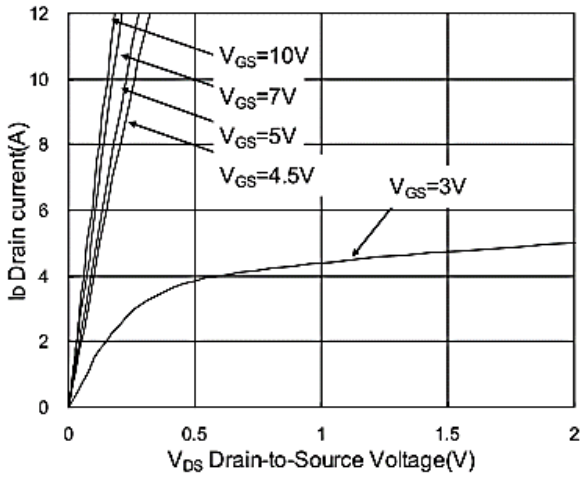
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	-8	A
$V_{SD}^e$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1.2	V

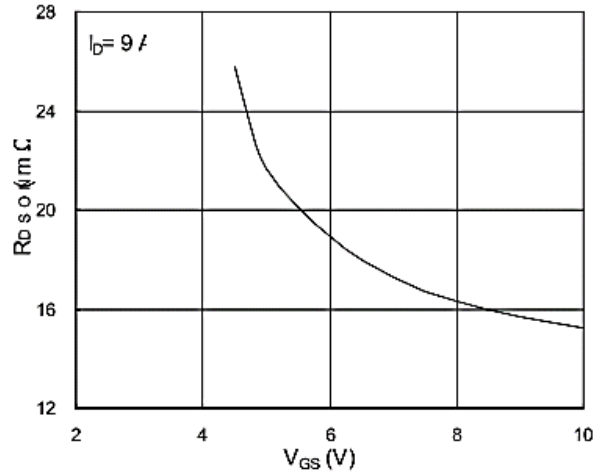
Note d : Pulse test; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

Note e : Guaranteed by design, not subject to production testing.

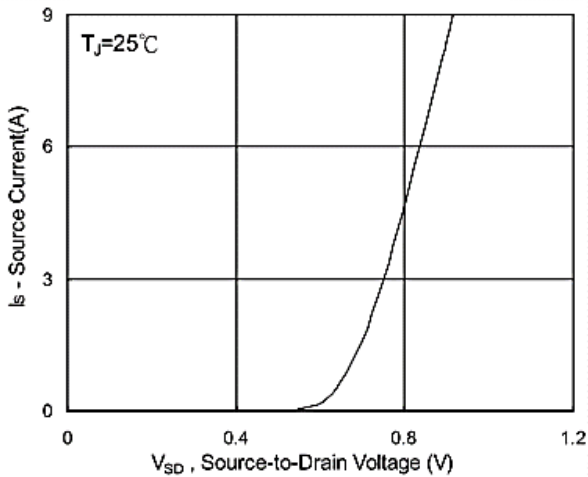
**N-Channel Typical Characteristics**



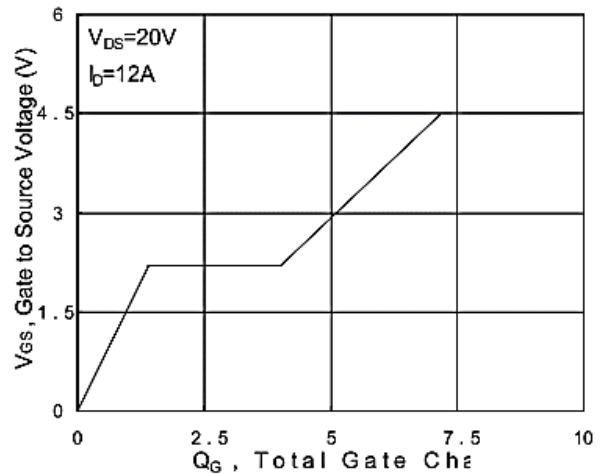
**Fig.1 Typical Output Characteristics**



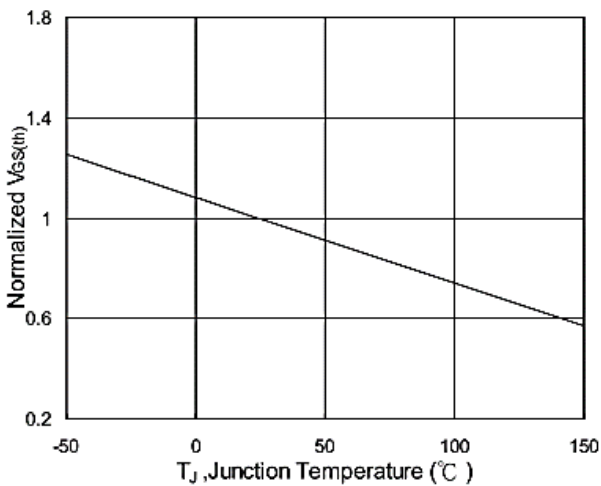
**Fig.2 On-Resistance v.s Gate-Source**



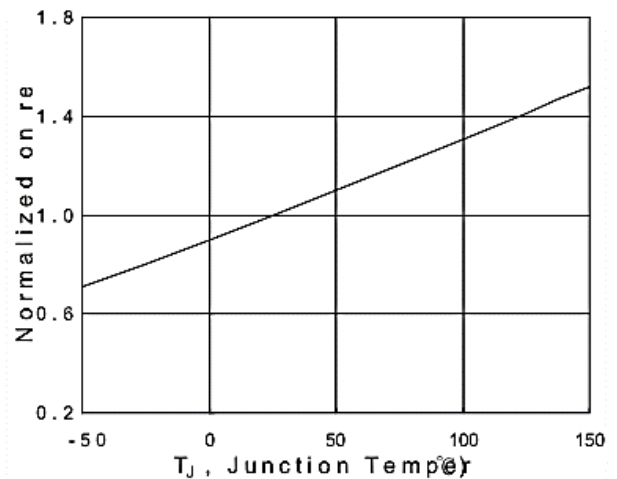
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge characteristics**

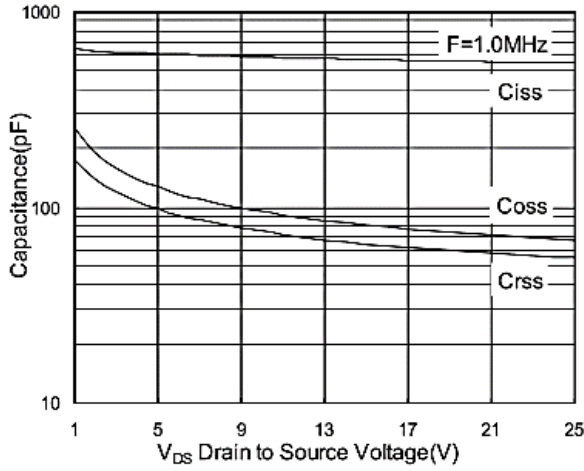


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

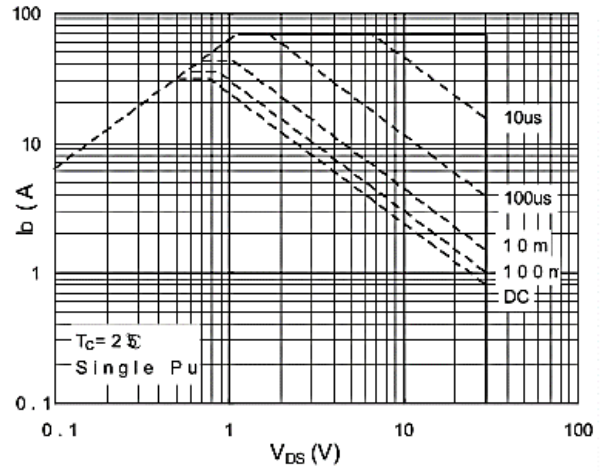


**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

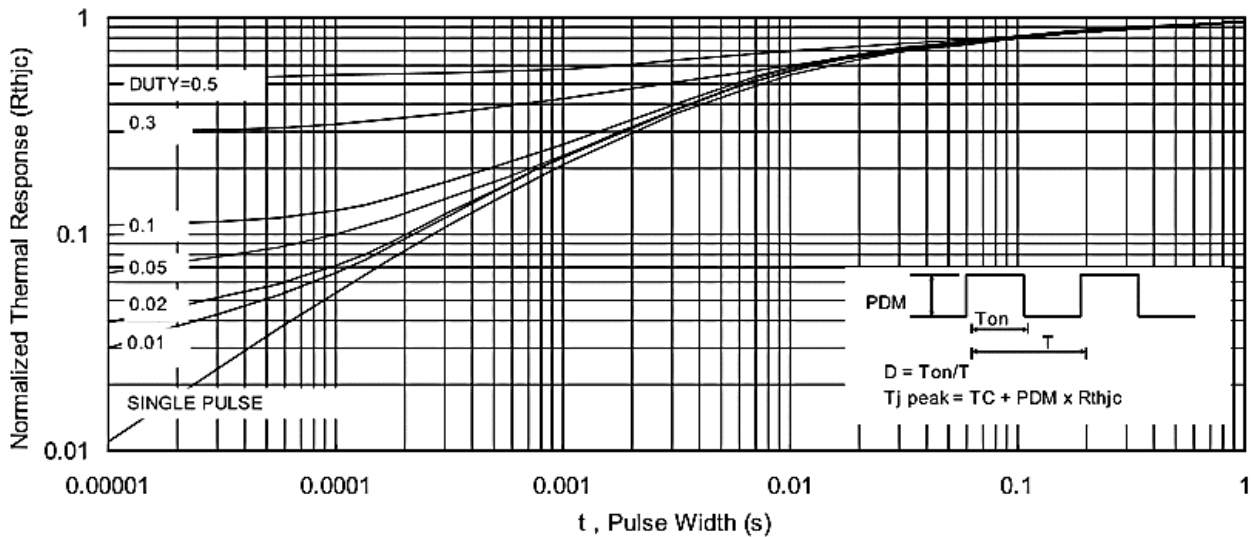
**N-Channel Typical Characteristics (Cont.)**



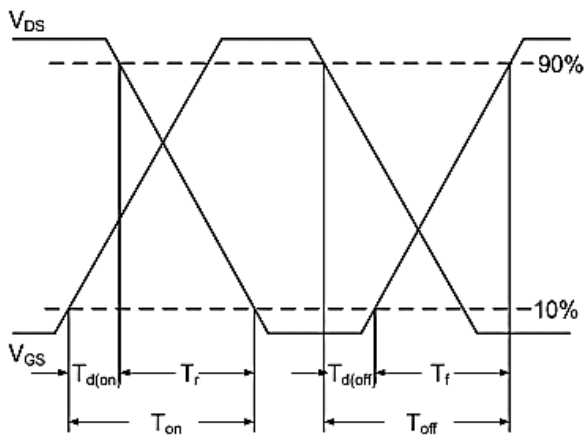
**Fig.7 Capacitance**



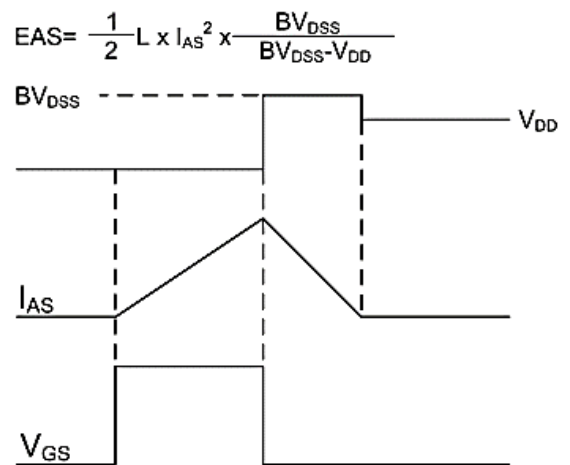
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

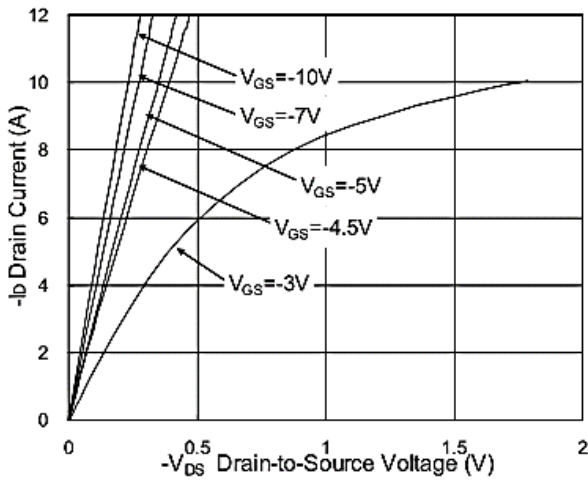


**Fig.10 Switching Time Waveform**

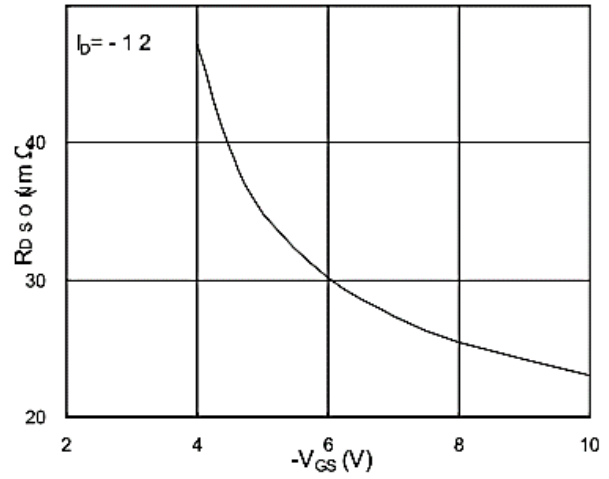


**Fig.11 Unclamped Inductive Waveform**

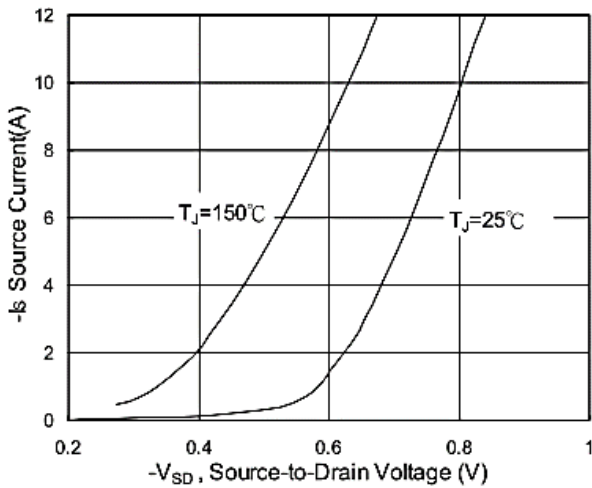
**P-Channel Typical Characteristics**



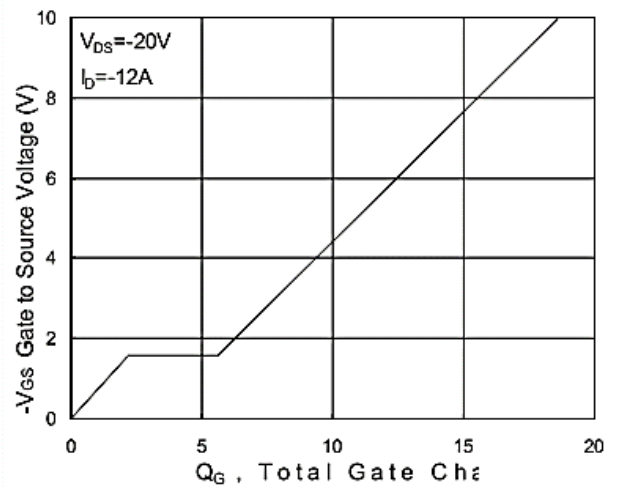
**Fig.1 Typical Output Characteristics**



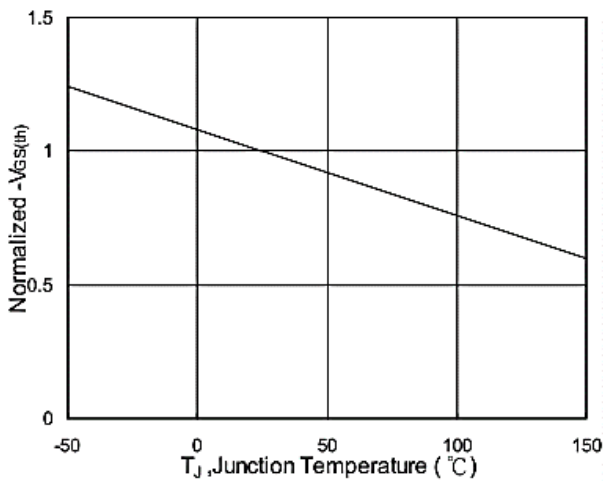
**Fig.2 On-Resistance v.s Gate-Source**



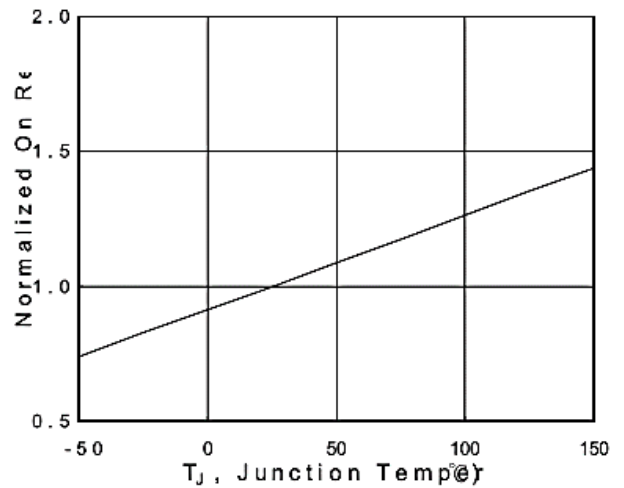
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge Characteristics**

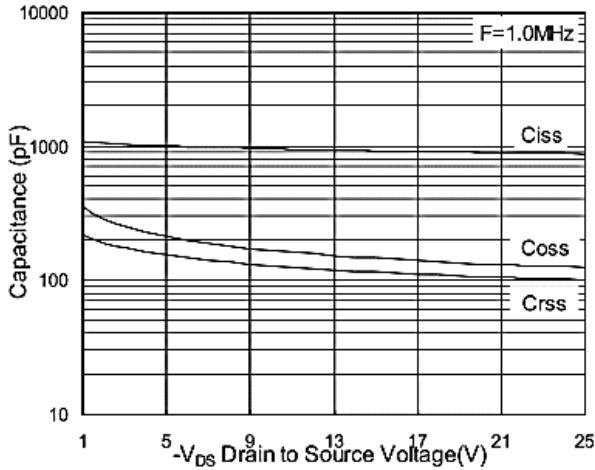


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

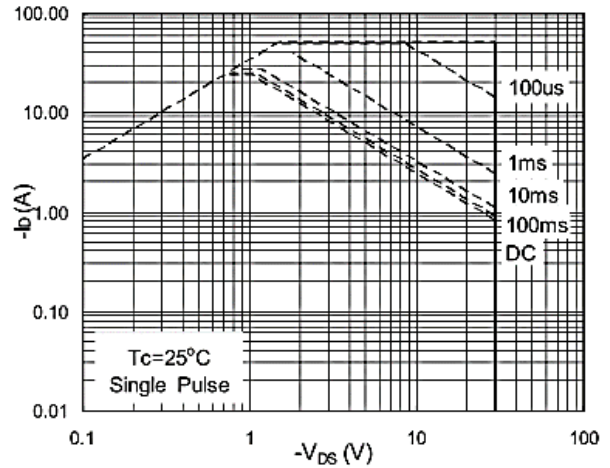


**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

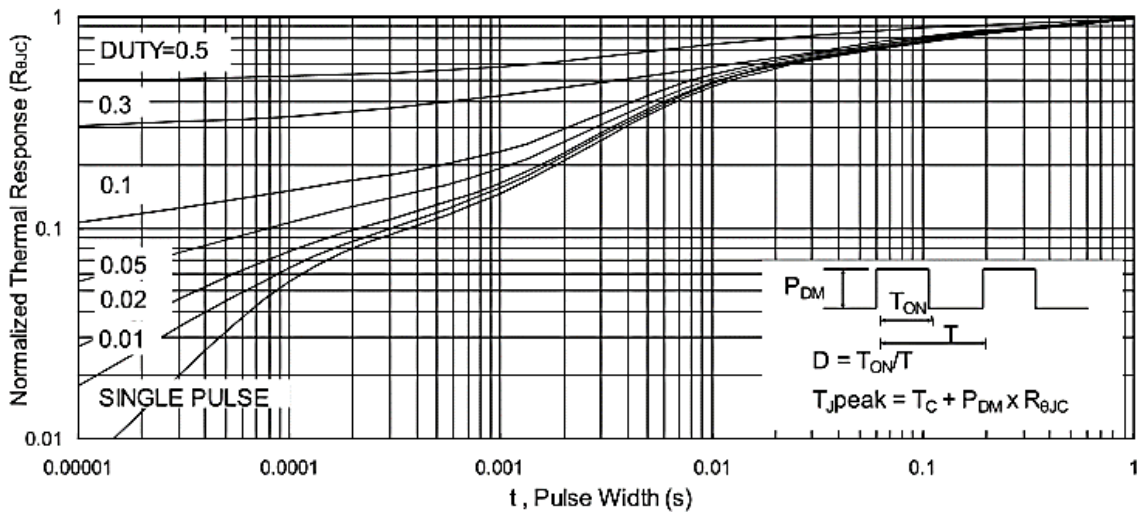
**P-Channel Typical Characteristics (Cont.)**



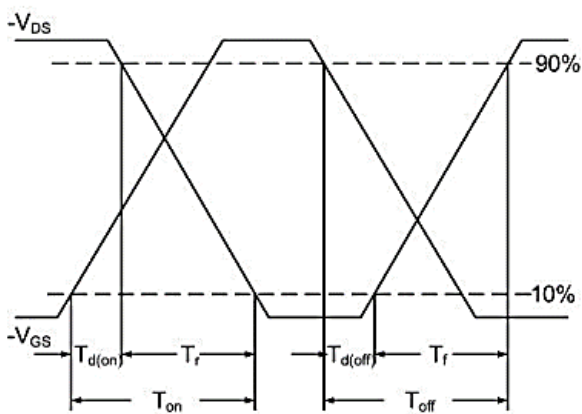
**Fig.7 Capacitance**



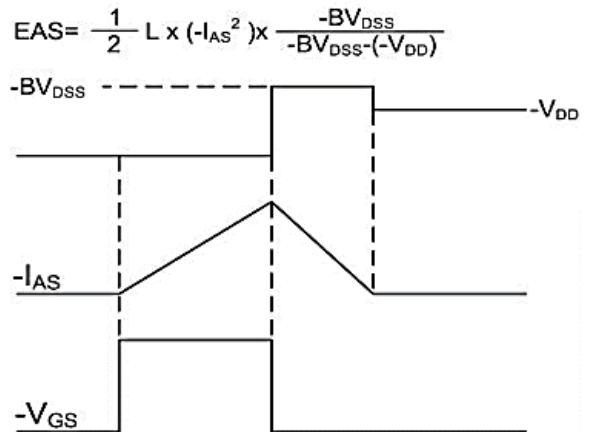
**Fig.8 Safe Operating Area**



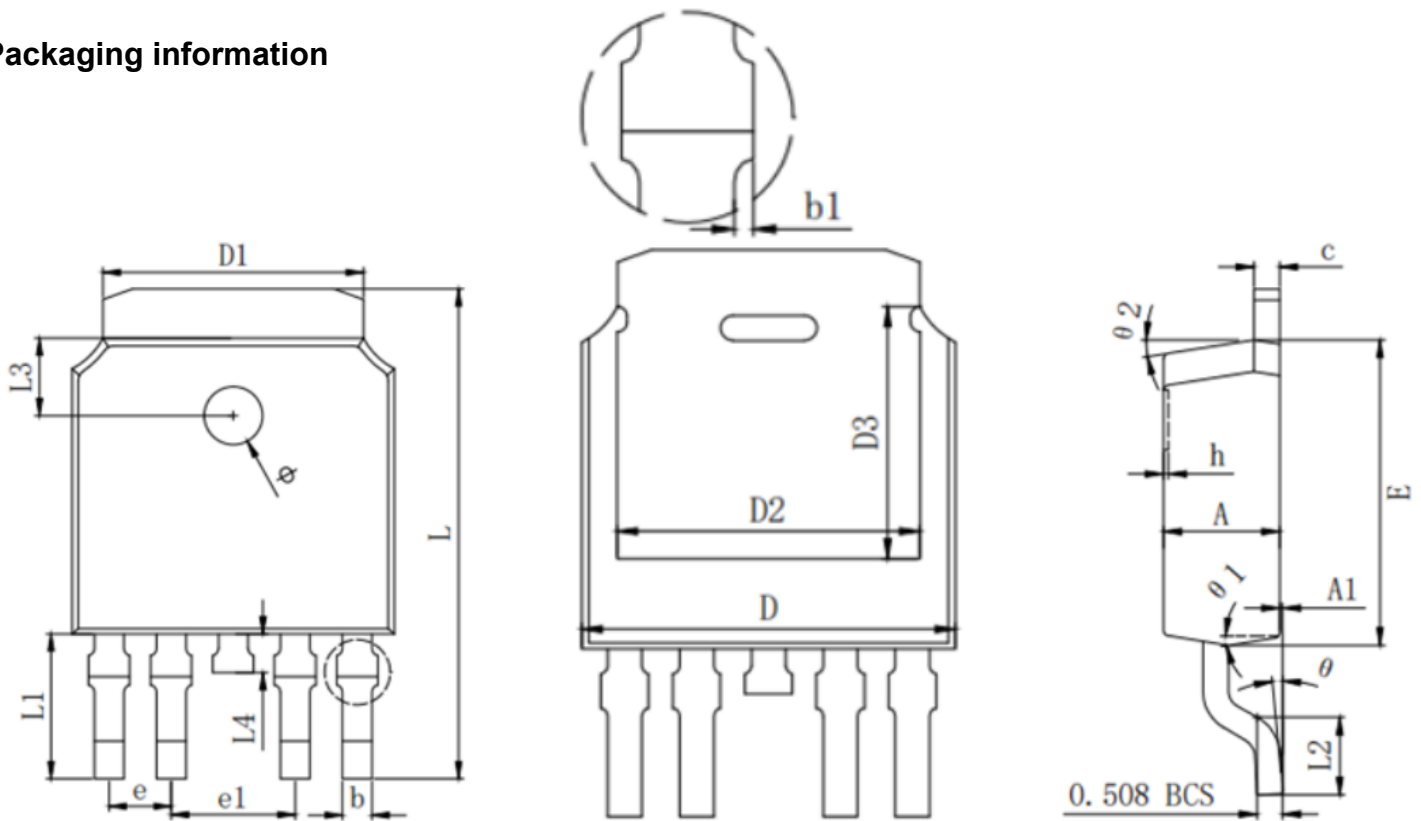
**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

**Packaging information**


SYMBOLS	MILLIMETERS		
	MIN.	Typ.	MAX.
A	2.200	2.300	2.400
A1	0.000	-	0.127
b	0.550	0.600	0.650
b1	0.000	-	0.120
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	5.346 REF		
D3	4.490 REF		
E	6.000	6.100	6.200
e	1.270 TYP		
e1	2.540 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.988 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.700	0.800	0.900
Φ	1.100	1.200	1.300
θ	0°	-	8°
θ 1	9° TYP		
θ 2	9° TYP		





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